

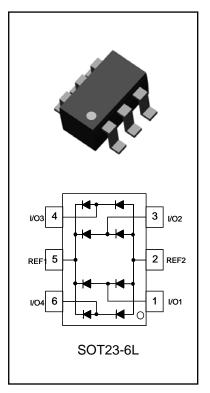


Low Capacitance Diode Array

This diode array is configured to protect up to four data transmission lines acting as a line terminator, minimizing overshoot and undershoot conditions due to bus impedance as well as protect against over-voltage events as electrostatic discharges.

SPECIFICATION FEATURES

- Maximum Capacitance of 3.0pF at 0Vdc 1MHz Line-to-Ground
- Peak Inverse voltage of 40V per diode
- Maximum Leakage Current of 1.0µA @ VR
- Industry Standard SMT Package SOT23-6L
- IEC61000-4-2, IEC61000-4-4 and IEC61000-4-5 Full Compliance
- 100% Tin Matte finish (LEAD-FREE PRODUCT)



APPLICATIONS

- USB 2.0 and Firewire Port Protection
- LAN/WLAN Access Point terminals
- Video Signal line protection



MAXIMUM RATINGS Tj = 25° C Unless otherwise noted

Rating	Symbol	Value	Units
Repetitive Peak Inverse Voltage	V_{RRM}	40	V
Continuous Reverse Voltage	V_{R}	40	V
Peak Pulse Current (8/20µs Waveform)	I _{PP}	24	А
Average Rectified Forward Current, Per Diode	I _{F(AV)}	50	mA
Power Dissipation, Tj = 85°C, I _F = 200mA, Per Diode	P_{D}	100	mW
Operating Junction Temperature Range	Tj	-55 to +150	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C
Soldering Temperature, t max = 10 s	TL	260	°C





ELECTRICAL CHARACTERISTICS Tj = 25°C unless otherwise noted

Parameter	Symbol	Conditions	Min	Тур	Max	Units
Repetitive Peak Inverse Voltage	V _{RRM}				40	V
Breakdown Voltage	V_{BR}	I _{BR} = 10μA	50			V
Forward Voltage (8/20µs Pulse)	V _F	I _{PP} = 1A			2.0	V
		I _{PP} = 10A			5.0	V
Reverse Leakage Current	I _R	$V_R = 40V$			1.0	μΑ
Off-State Junction Capacitance	CJ	0Vdc Bias, f =1 MHz Between I/O pins and REF2 (Ground)			3.0	pF
		0Vdc Bias, f =1 MHz Between I/O pins		2.0		pF





PACKAGE DIMENSIONS AND SUGGESTED PAD LAYOUT

